

Amendments to the Specification:

In the title:

Please change the title to read as follows:

"REDUCED-SIZE MULTI-CHIP MODULE WITH HIGH-SPEED SIGNAL EXCHANGE"

Please replace the paragraph beginning on page 6, line 2 with the following amended paragraph:

The semiconductor chips SH, SDRAM and ASIC shown in FIG. 2 are mounted on one main surface of the mounting board in such a manner that the ~~circuit formed~~ circuit-formed surfaces of the semiconductor chips are in opposed relation to each other the mounting board. A plurality of external terminals of the multi-chip module are arranged on the other main surface of the mounting board. This configuration makes possible a compact multi-chip module regardless of the area occupied by the plurality of the semiconductor chips and the area required for arranging the plurality of the external terminals.

Please replace the paragraph beginning on page 15, line 25 with the following amended paragraph:

As shown in FIG. 10, the MCM according to this embodiment has a basically similar configuration to the MCM described with reference to FIGS. 1 to 8 above except for the difference described below. Specifically, the [[AU]] Au stud bumps 1 are each electrically and mechanically connected to the connector 4 of the mounting board 3 through a coupling member 2. Between the semiconductor chip 5 and the mounting board 3, an underfill resin 6 is filled to suppress the damage to the semiconductor chip 5 which otherwise might be caused by the concentration of thermal stress due to the difference in the coefficient of thermal expansion between the mounting board 3 and the semiconductor chip 5. Further, the reverse side of the mounting board 3 is formed with land electrodes 7 as external terminals for electrically connecting a printed wiring board (PCB), for example.